



1771
Docket No.: KCC-16,631

THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants: Peiguang ZHOU, et al.

Group No. 1771

Serial No.: 09/944,635

Examiner: L. Salvatore

Filing Date: 31 August 2001

Title: HOT-MELT ADHESIVE FOR
NON-WOVEN ELASTIC COMPOSITE
BONDING

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TC 1700

AMENDMENT

Assistant Commissioner for Patents
Washington, D.C. 20231

Dear Sir:

In response to the Office Action mailed 29 August 2002, please amend
the above-identified patent application as follows:

IN THE SPECIFICATION:

Please replace the paragraph at page 5, lines 20-21, with the following
rewritten paragraphs:

I hereby certify that this correspondence (along with any paper referred to as being attached or enclosed) is being deposited with the United States Postal Service as First Class Mail in an envelope addressed to: Assistant Commissioner for Patents, Washington, D.C. 20231 on

October 18, 2002

10/18/02
Date

Signature

John J. Brady